

Workshop for Establishment of the IEEE CPMT Nordic Chapter

In celebration of the formation of the IEEE CPMT Nordic Chapter, the first gathering of the members of the new IEEE CPMT Nordic Chapter has gathered in the workshop on nanoscale electronics packaging in June 10 2016 in Gothenburg, Sweden. The purpose of this workshop is to provide a central platform for engineers and researchers within related areas to share and extend their network.

Twelve talks by distinguished guest speaker from industry and academics were presented. This workshop focused on novel nanoscale materials and devices which will ultimately lead to new solutions to the heterogeneous integration of semiconductor devices and microsystems. The workshop invites talks and presentations that document new developments in materials, processes, characterization techniques, and facilities for the realization of those new concepts. The impact on the paradigm shifts, such as More than Moore and Beyond Moore, in the semiconductor industry with these potential new applications in the packaging domain was also discussed. After the workshop, the first constitutive IEEE CPMT Nordic Chapter interim board meeting was held. It was concluded that the involvement of Finland is very much welcomed. It is proposed that the meeting in the form of meeting/conference/seminars and chairmanship should be rotated between the Nordic countries and Baltic countries. The next meeting will be held in 2016 and Norway is proposed as the host country. Finland suggested for 2017. Also collaboration with IMAPS Nordic chapter is planned. The best scenario is that IMAPS Nordic conference will run in one year and the second year run by IEEE CPMT Nordic Chapter. Then we help each other to technically back up the conference.

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